

2. Reverse Recovery Test Conditions: I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

3. Thermal Resistance from Junction to Ambient, Lead Length = 1/2" on P.C. Board with 1.5" x 1.5" Copper Surface.

4. Pulse lest: tp = 300 uS, Duty Cycle < 2%.



